PMEG2010BELD

20 V, 1 A low VF MEGA Schottky barrier rectifier

Rev. 1 — 18 April 2012 **Product data sheet**

1. Product profile

1.1 General description

Planar Maximum Efficiency General Application (MEGA) Schottky barrier rectifier with an integrated guard ring for stress protection, encapsulated in a leadless ultra small DFN1006D-2 (SOD882D) Surface-Mounted Device (SMD) plastic package with visible and solderable side pads.

1.2 Features and benefits

- Average forward current: $I_{F(AV)} \leq 1$ A
- Reverse voltage: $V_R \leq 20$ V
- Low forward voltage $V_F \leq 490$ mV
- AEC-Q101 qualified
- Ultra small and leadless SMD plastic package
- Solderable side pads
- Package height typ. 0.37 mm

1.3 Applications

- Low voltage rectification
- High efficiency DC-to-DC conversion
- Switch mode power supply
- Reverse polarity protection
- Low power consumption applications
- Ultra high-speed switching
- LED backlight for mobile application

1.4 Quick reference data

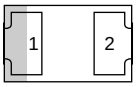
Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$I_{F(AV)}$	average forward current	δ = 0.5 ; f = 20 kHz; $T_{amb} \leq 80$ °C; square wave	[1]	-	-	1	A
		δ = 0.5 ; f = 20 kHz; $T_{sp} \leq 130$ °C; square wave		-	-	1	A
V_R	reverse voltage	T_j = 25 °C		-	-	20	V
V_F	forward voltage	I_F = 1 A; pulsed; $t_p \leq 300$ µs; δ ≤ 0.02 ; T_j = 25 °C		-	428	490	mV
I_R	reverse current	V_R = 10 V; T_j = 25 °C		-	28	50	µA
t_{rr}	reverse recovery time	I_R = 0.5 A; I_F = 0.5 A; $I_{R(meas)}$ = 0.1 A; T_j = 25 °C		-	1.6	-	ns

[1] Device mounted on a ceramic PCB, Al_2O_3, standard footprint.

2. Pinning information

Table 2. Pinning information

Pin	Symbol	Description	Simplified outline	Graphic symbol
1	K	cathode[1]	 Transparent top view **DFN1006D-2 (SOD882D)**	*sym001*
2	A	anode		

[1] The marking bar indicates the cathode.

3. Ordering information

Table 3. Ordering information

Type number	Package		
	Name	Description	Version
PMEG2010BELD	DFN1006D-2	Leadless ultra small plastic package; 2 terminals	SOD882D

4. Marking

Table 4. Marking codes

Type number	Marking code
PMEG2010BELD	0000 1001

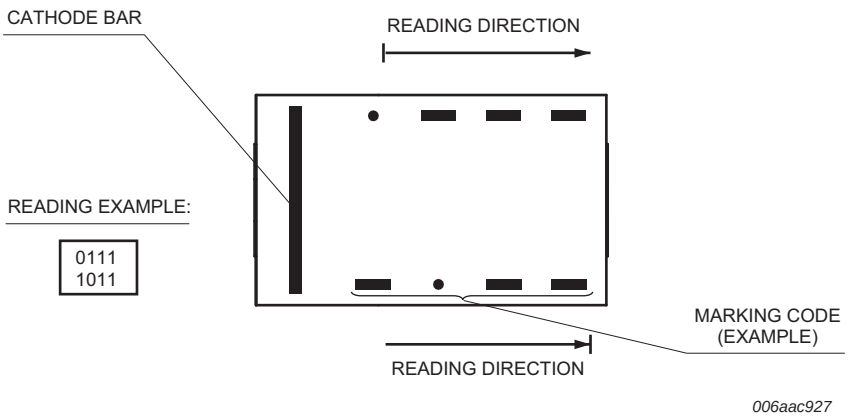


Fig 1. DFN1006D-2 (SOD882D) binary marking code description

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5. Limiting values

Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V_R	reverse voltage	T_j = 25 °C		-	20	V
I_F	forward current	T_{sp} ≤ 130 °C		-	1	A
$I_{F(AV)}$	average forward current	δ = 0.5 ; f = 20 kHz; square wave; T_{amb} ≤ 80 °C	[1]	-	1	A
		δ = 0.5 ; f = 20 kHz; square wave; T_{sp} ≤ 130 °C		-	1	A
I_{FRM}	repetitive peak forward current	t_p ≤ 1 ms; δ ≤ 0.25		-	3	A
I_{FSM}	non-repetitive peak forward current	t_p = 8 ms; $T_{j(init)}$ = 25 °C; square wave		-	6	A
P_{tot}	total power dissipation	T_{amb} ≤ 25 °C	[2][3]	-	370	mW
			[4][3]	-	735	mW
			[1][3]	-	1135	mW
T_j	junction temperature			-	150	°C
T_{amb}	ambient temperature			-55	150	°C
T_{stg}	storage temperature			-65	150	°C

[1] Device mounted on a ceramic PCB, Al_2O_3, standard footprint.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Reflow soldering is the only recommended soldering method.

[4] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated, mounting pad for cathode 1 cm^2.

6. Thermal characteristics

Table 6. Thermal characteristics

Symbol	Parameter	Conditions		Min	Typ	Max	Unit
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air	[1][2][3]	-	-	340	K/W
			[1][4][3]	-	-	170	K/W
			[1][5][3]	-	-	110	K/W
$R_{th(j-sp)}$	thermal resistance from junction to solder point		[6]	-	-	25	K/W

[1] For Schottky barrier diodes thermal runaway has to be considered, as in some applications the reverse power losses P_R are a significant part of the total power losses.

[2] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[3] Reflow soldering is the only recommended soldering method.

[4] Device mounted on an FR4 PCB, single-sided copper, tin-plated, mounting pad for cathode 1 cm^2.

[5] Device mounted on a ceramic PCB, Al_2O_3, standard footprint.

[6] Soldering point of cathode tab.

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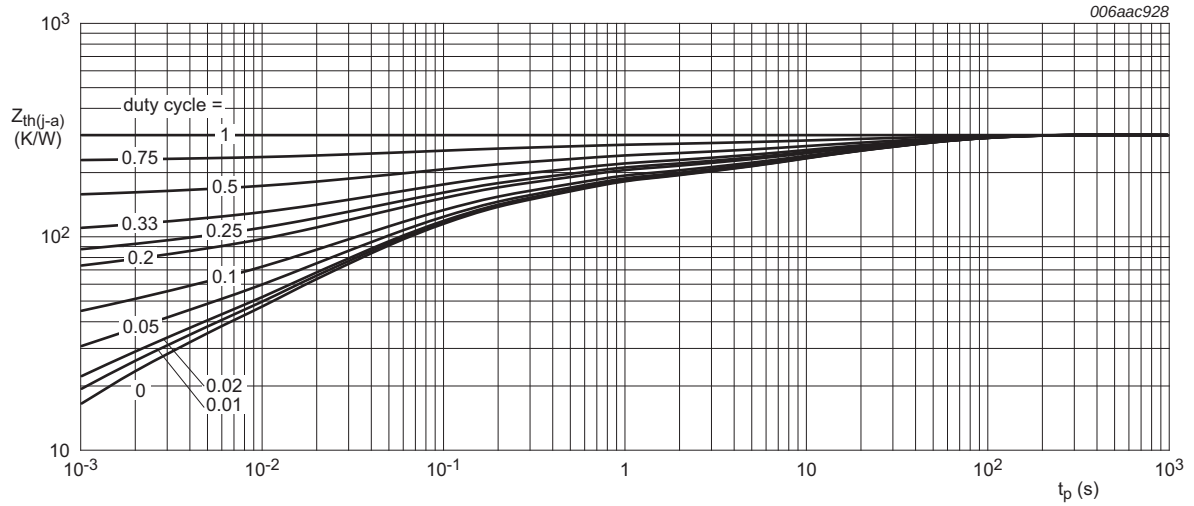
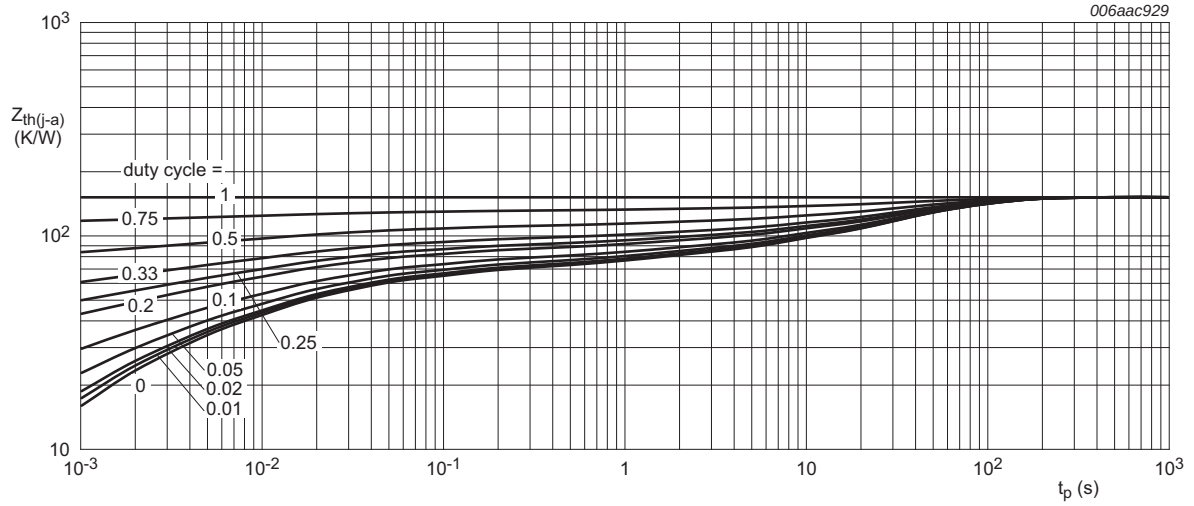


FR4 PCB, standard footprint

Fig 2. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values



FR4 PCB, mounting pad for cathode 1 cm^2

Fig 3. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

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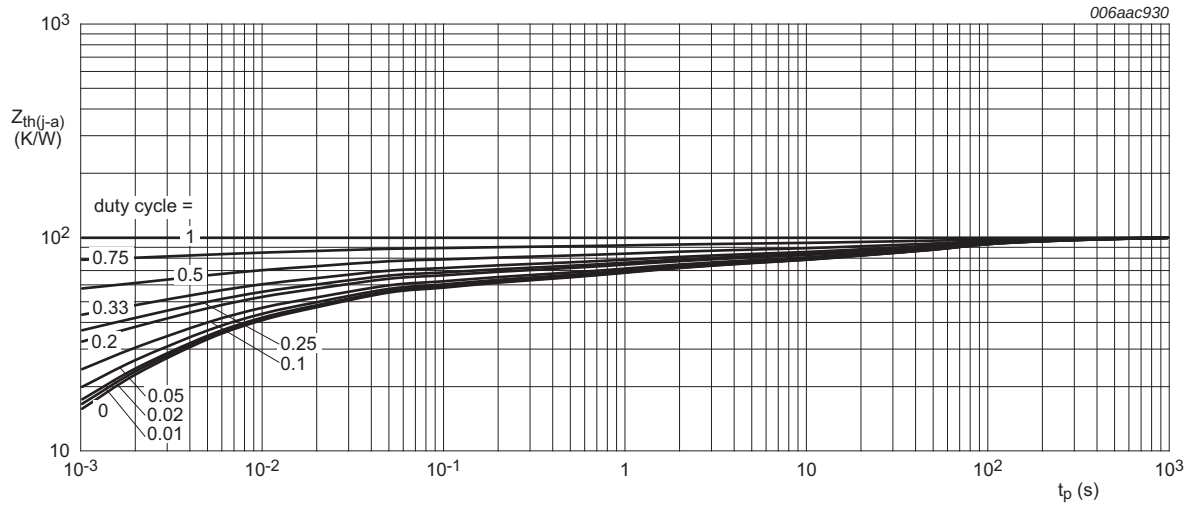

Ceramic PCB, Al_2O_3, standard footprint

Fig 4. Transient thermal impedance from junction to ambient as a function of pulse duration; typical values

7. Characteristics

Table 7. Characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V_F	forward voltage	I_F = 100 mA; pulsed; $t_p \leq 300$ µs; $\delta \leq 0.02$; T_j = 25 °C	-	266	310	mV
		I_F = 500 mA; pulsed; $t_p \leq 300$ µs; $\delta \leq 0.02$; T_j = 25 °C	-	353	390	mV
		I_F = 1 A; pulsed; $t_p \leq 300$ µs; $\delta \leq 0.02$; T_j = 25 °C	-	428	490	mV
I_R	reverse current	V_R = 10 V; T_j = 25 °C	-	28	50	µA
		V_R = 20 V; T_j = 25 °C	-	87	200	µA
C_d	diode capacitance	V_R = 1 V; f = 1 MHz; T_j = 25 °C	-	31	40	pF
t_{rr}	reverse recovery time	I_F = 0.5 A; I_R = 0.5 A; $I_{R(meas)}$ = 0.1 A; T_j = 25 °C	-	1.6	-	ns
V_{FRM}	forward recovery voltage	I_F = 0.5 A; dI_F/dt = 20 A/µs; T_j = 25 °C	-	565	-	mV

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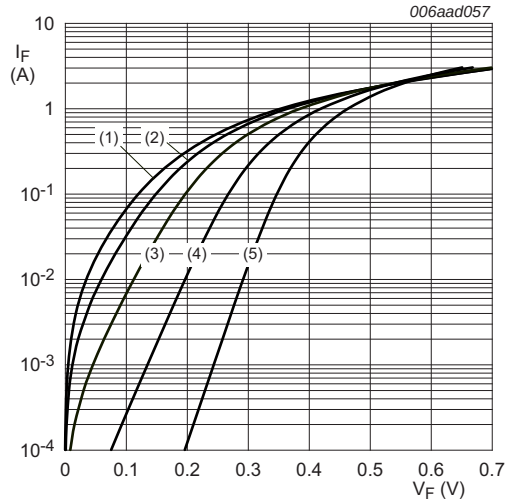
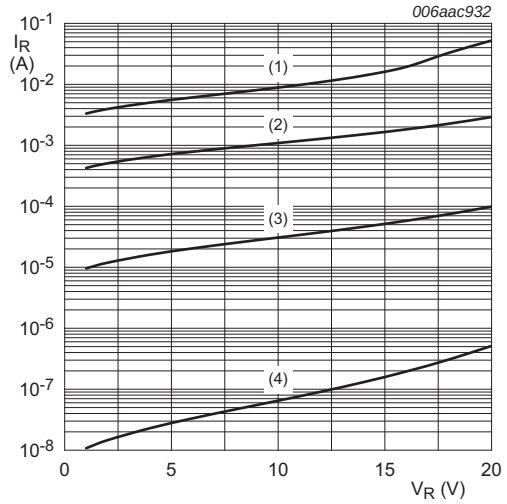


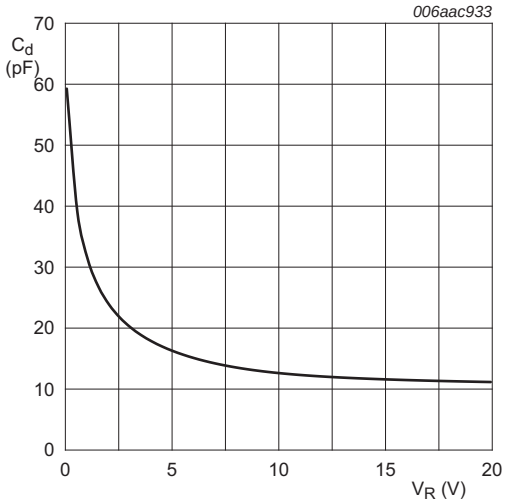
(1) T_j = 150 °C
(2) T_j = 125 °C
(3) T_j = 85 °C
(4) T_j = 25 °C
(5) T_j = −40 °C

Fig 5. Forward current as a function of forward voltage; typical values



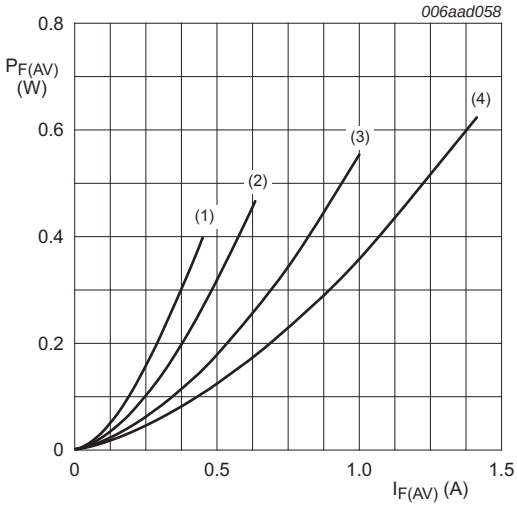
(1) T_j = 125 °C
(2) T_j = 85 °C
(3) T_j = 25 °C
(4) T_j = −40 °C

Fig 6. Reverse current as a function of reverse voltage; typical values



f = 1 MHz; T_{amb} = 25 °C

Fig 7. Diode capacitance as a function of reverse voltage; typical values



T_j = 150 °C
(1) δ = 0.1
(2) δ = 0.2
(3) δ = 0.5
(4) δ = 1

Fig 8. Average forward power dissipation as a function of average forward current; typical values

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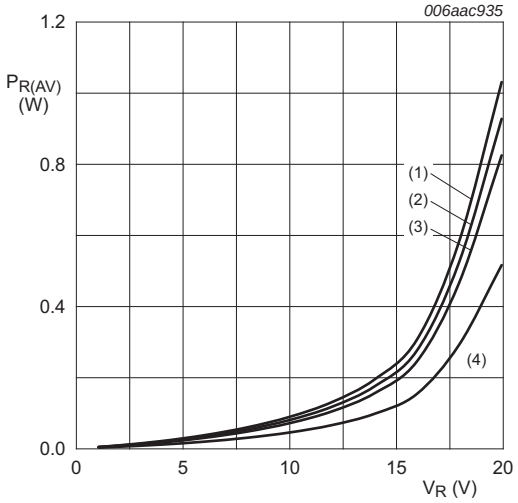


T_j = 125 °C

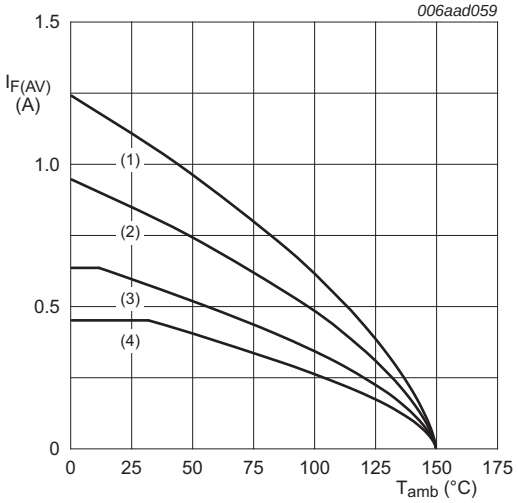
(1) δ = 1 (DC)

(2) δ = 0.9; f = 20 kHz

(3) δ = 0.8; f = 20 kHz

(4) δ = 0.5; f = 20 kHz

Fig 9. Average reverse power dissipation as a function of reverse voltage; typical values



FR4 PCB, standard footprint

T_j = 150 °C

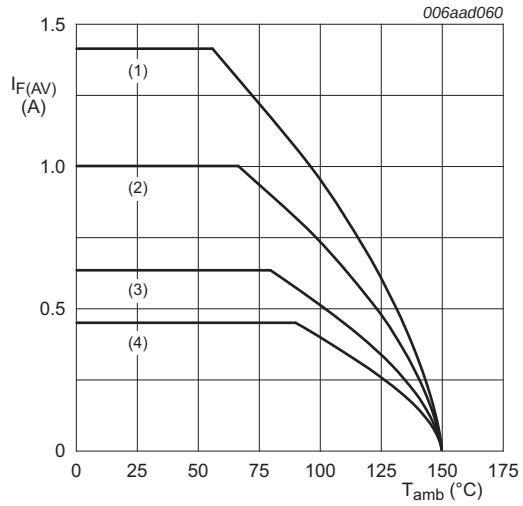
(1) δ = 1

(2) δ = 0.5

(3) δ = 0.2

(4) δ = 0.1

Fig 10. Average forward current as a function of ambient temperature; typical values



FR4 PCB, mounting pad for cathode 1 cm^2

T_j = 150 °C

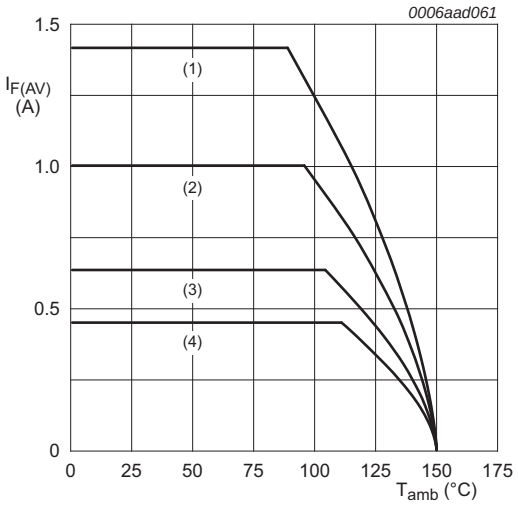
(1) δ = 1

(2) δ = 0.5

(3) δ = 0.2

(4) δ = 0.1

Fig 11. Average forward current as a function of ambient temperature; typical values



Ceramic PCB, Al_2O_3, standard footprint

T_j = 150 °C

(1) δ = 1

(2) δ = 0.5

(3) δ = 0.2

(4) δ = 0.1

Fig 12. Average forward current as a function of ambient temperature; typical values

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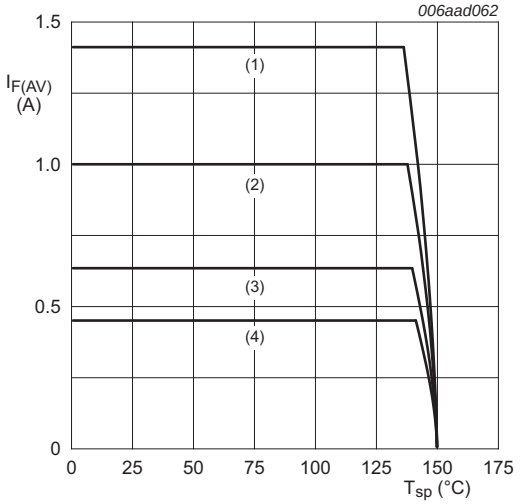

T_j = 150 °C

(1) δ = 1

(2) δ = 0.5

(3) δ = 0.2

(4) δ = 0.1

Fig 13. Average forward current as a function of solder point temperature; typical values

8. Test information

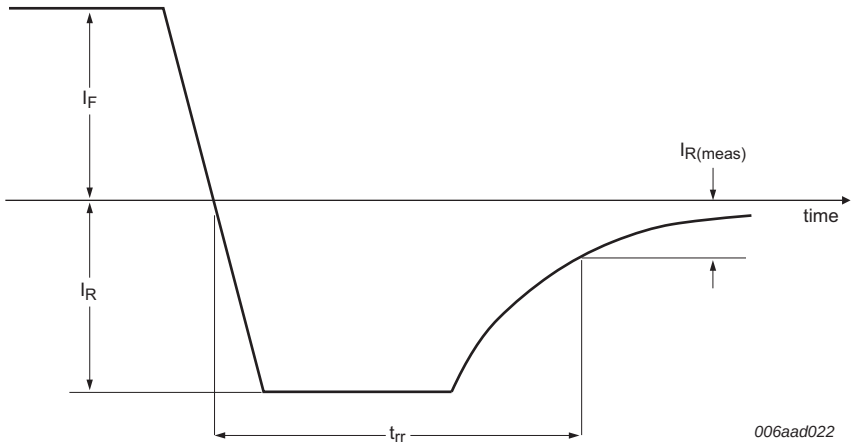

Fig 14. Reverse recovery definition

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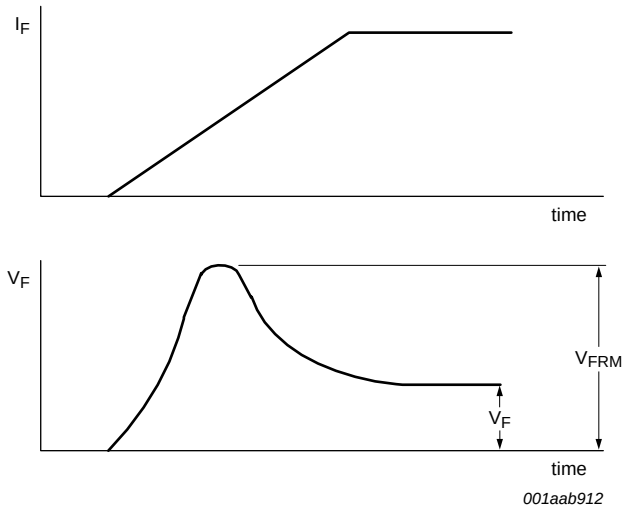

Fig 15. Forward recovery definition

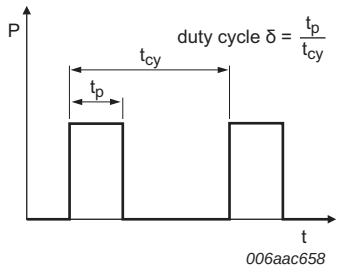

Fig 16. Duty cycle definition

The current ratings for the typical waveforms are calculated according to the equations: $I_{F(AV)} = I_M \times \delta$ with I_M defined as peak current, $I_{RMS} = I_{F(AV)}$ at DC, and $I_{RMS} = I_M \times \sqrt{\delta}$ with I_{RMS} defined as RMS current.

8.1 Quality information

This product has been qualified in accordance with the Automotive Electronics Council (AEC) standard Q101 - Stress test qualification for discrete semiconductors, and is suitable for use in automotive applications.

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9. Package outline

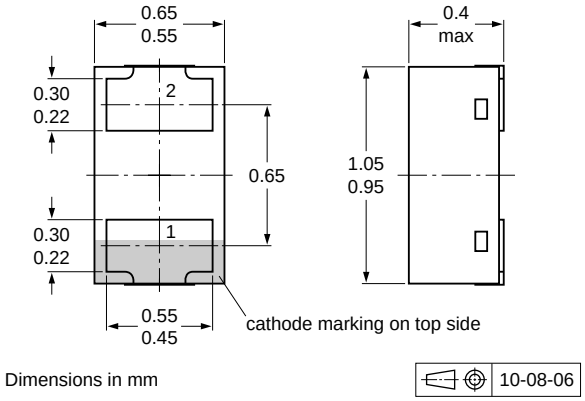

Fig 17. Package outline DFN1006D-2 (SOD882D)

10. Soldering

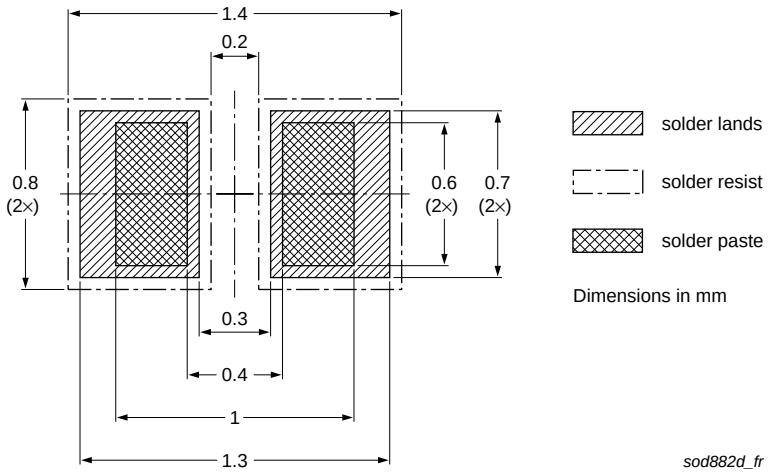

Fig 18. Reflow soldering footprint for DFN1006D-2 (SOD882D)

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11. Revision history

Table 8. Revision history

Document ID	Release date	Data sheet status	Change notice	Supersedes
PMEG2010BELD v.1	20120418	Product data sheet	-	-

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12. Legal information

12.1 Data sheet status

Document status[1] [2]	Product status[3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
Product [short] data sheet	Production	This document contains the product specification.

[1] Please consult the most recently issued document before initiating or completing a design.

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Date of release: 18 April 2012
Document identifier: PMEG2010BELD